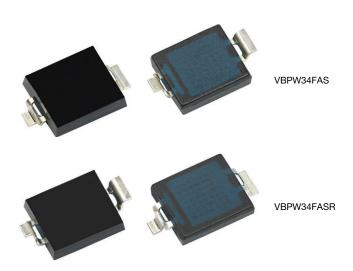


RoHS

HALOGEN FREE

Silicon PIN Photodiode



DESCRIPTION

VBPW34FAS and VBPW34FASR are high speed and high sensitive PIN photodiodes. It is a surface mount device (SMD) including the chip with a 7.5 mm² sensitive area and a daylight blocking filter matched with IR emitters operating at wavelength 870 nm or 950 nm.

FEATURES

- Package type: surface-mount
- · Package form: GW, RGW



- Radiant sensitive area (in mm²): 7.5
- · High radiant sensitivity
- Daylight blocking filter matched with 870 nm to 950 nm emitters
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 65^{\circ}$
- Floor life: 168 h, MSL 3, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- High speed detector for infrared radiation
- Infrared remote control and free air data transmission systems, e.g. in combination with TSFFxxxx series IR emitters

PRODUCT SUMMARY					
COMPONENT	I _{ra} (μΑ)	φ (°)	λ _{0.5} (nm)		
VBPW34FAS	55	± 65	780 to 1050		
VBPW34FASR	55	± 65	780 to 1050		

Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATIO	N			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VBPW34FAS	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Gullwing	
VBPW34FASR	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Reverse gullwing	

Note

• MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V_{R}	60	V	
Power dissipation	T _{amb} ≤ 25 °C	P _V	215	mW	
Junction temperature		T _j	100	°C	
Operating temperature range		T _{amb}	-40 to +100	°C	
Storage temperature range		T _{stg}	-40 to +100	°C	
Soldering temperature	According to reflow sloder profile Fig. 8	T _{sd}	260	°C	
Thermal resistance junction to ambient		R _{thJA}	350	K/W	

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V _F	-	1	1.3	V
Breakdown voltage	I _R = 100 μA, E = 0	V _(BR)	60	-	-	V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}	-	2	30	nA
Diode capacitance	V _R = 0 V, f = 1 MHz, E = 0	C_D	_	70	-	pF
	V _R = 3 V, f = 1 MHz, E = 0	C _D	-	25	40	pF
Open circuit voltage	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	Vo	-	350	-	mV
Temperature coefficient of Vo	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	TK _{Vo}	-	-2.6	-	mV/K
Short circuit current	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	I _k	-	50	-	μΑ
Temperature coefficient of I _k	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	TK _{lk}	-	0.1	-	%/K
Reverse light current	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 950 \text{ nm}$, $V_R = 5 \text{ V}$	I _{ra}	45	55	-	μΑ
Angle of half sensitivity		φ	_	± 65	-	0
Wavelength of peak sensitivity		λ_{p}	-	950	-	nm
Range of spectral bandwidth		λ 0.5	-	780 to 1050	-	nm
Noise equivalent power	V _R = 10 V, λ = 950 nm	NEP	-	4 x 10 ⁻¹⁴	-	W/√Hz
Rise time	$V_R = 10 \text{ V}, R_L = 1 \text{ k}\Omega, \lambda = 820 \text{ nm}$	t _r	-	100	1	ns
Fall time	$V_R = 10 \text{ V}, R_L = 1 \text{ k}\Omega, \lambda = 820 \text{ nm}$	t _f	-	100	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

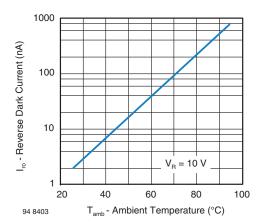


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

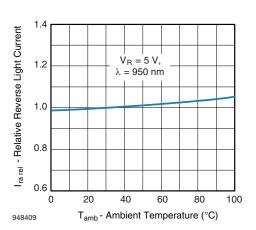


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

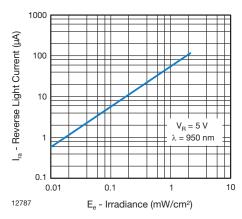


Fig. 3 - Reverse Light Current vs. Irradiance

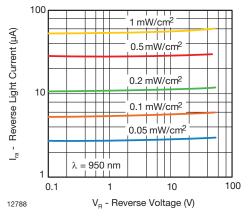


Fig. 4 - Reverse Light Current vs. Reverse Voltage



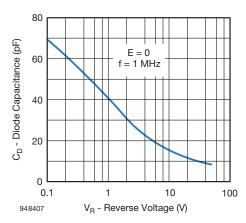


Fig. 5 - Diode Capacitance vs. Reverse Voltage

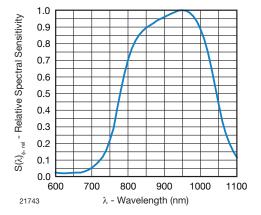


Fig. 6 - Relative Spectral Sensitivity vs. Wavelength

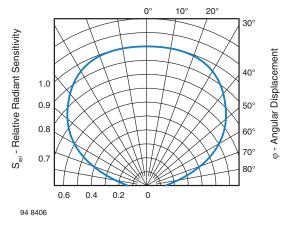
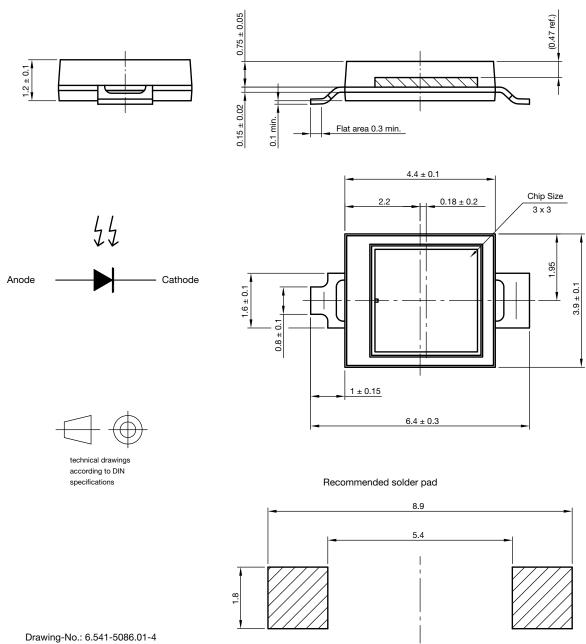


Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement



PACKAGE DIMENSIONS FOR VBPW34FAS in millimeters

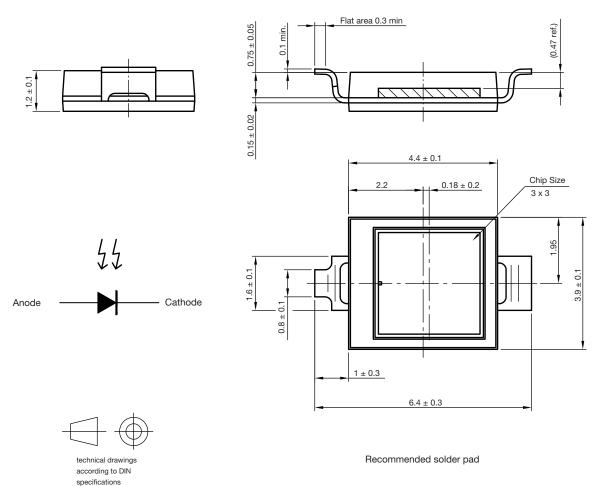


Issue: 1; 15.04.10

22105



PACKAGE DIMENSIONS FOR VBPW34FASR in millimeters



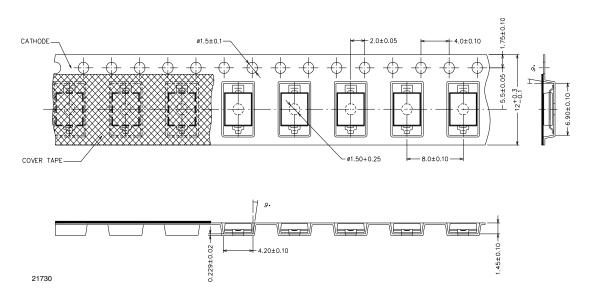
8.9 5.4

Drawing-No.: 6.541-5085.01-4

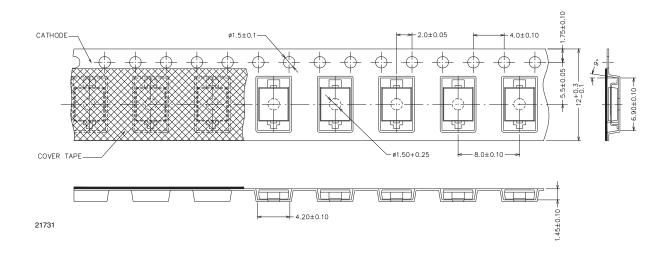
Issue: 1; 15.04.10

22104

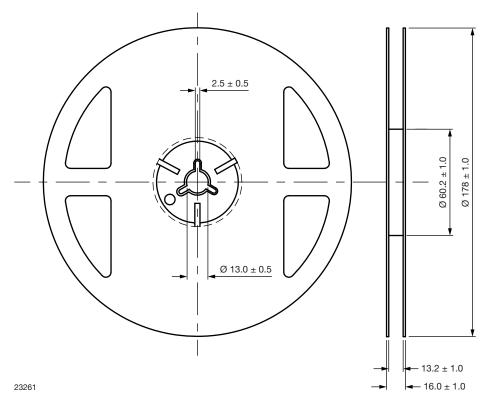
TAPING DIMENSIONS FOR VBPW34FAS in millimeters



TAPING DIMENSIONS FOR VBPW34FASR in millimeters



REEL DIMENSIONS FOR VBPW34FAS AND VBPW34FASR in millimeters



SOLDER PROFILE

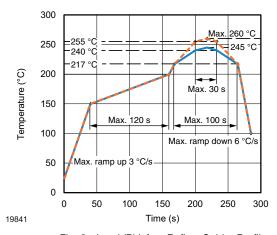


Fig. 8 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

Conditions: T_{amb} < 30 °C, RH < 60 %

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or recommended conditions:

192 h at 40 °C (+ 5 °C), RH < 5 %

or

96 h at 60 °C (+ 5 °C), RH < 5 %



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Vishay

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